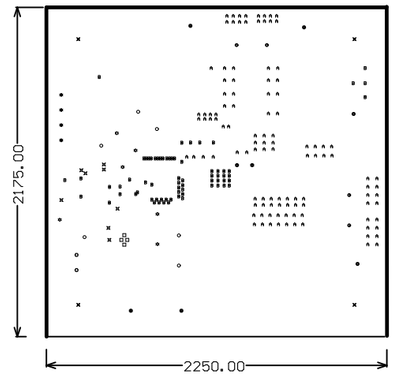
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	2.80mil		
4	Dielectric1	FR-4	5.00mil	4.2	
5	MidLayer1	Copper	2.80mil		
6	Dielectric2	FR-4	40.00mil	4.2	
7	MidLayer2	Copper	2.80mil		
8	Dielectric 3	FR-4	5.00mil	4.2	
9	Bottom Layer	Copper	2.80mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

Symbol	Count	Hole Size	Plated	Hole Type
	2	1.300mm (51.18mil)	PTH	Round
	4	0.200mm (7.87mil)	PTH	Round
	4	1.000mm (39.37mil)	PTH	Round
	4	1.400mm (55.12mil)	PTH	Round
	4	3.200mm (125.98mil)	PTH	Round
	6	0.813mm (32.00mil)	PTH	Round
	6	1.067mm (42.00mil)	PTH	Round
	8	0.254mm (10.00mil)	PTH	Round
	8	1.016mm (40.00mil)	PTH	Round
B	69	0.203mm (8.00mil)	PTH	Round
ADrill Table	110	0.305mm (12.00mil)	PTH	Round
	225 Total			



1000 (mil)

DESIGN INFORMATION

BOARD SIZE (REFER ALSO ARRAY/PANEL PROFILING INFORMATION)
2400MIL X 2700

Number of Layers : 4
MIN. TRACK WIDTH: 5 MIL
MIN. CLEARANCE: 4 MIL
MIN. VIA PAD SIZE: 18 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
COPPER THICKNESS (FINISHED):
OUTER: [ ] 1.4MIL (1oz) [ ] 2MIL (1.4oz) [X] 2.8MIL (2oz)
INNER SIGNAL: [ ] 1.4MIL (1oz) [X] 2.8MIL (2oz) [ ] N/A
DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH MIN COPPER THICKNESS: [X] 1MIL [ ] OTHER
BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR:
[X] GREEN [ ] BLUE [ ] OTHER
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER
ARRAY/PANEL: [ ] CUT AND TRIM PER MECH LAYER 1
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] UL 94V-0 [X] RoHS [ ] OTHER PER ORDER
ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER
MANUFACTURER'S UL: [ ] RAIL [ ] METAL [X] SILK

Texas Instruments

PROJECT TITLE: LMG1205 GaN Half-Bridge Driver EVM
DESIGNED FOR: Public Release
FILE NAME: SV601338E1_PCB.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: SV601338	REV: E1	SVN REV: Not In VersionControl
LAYER NAME = [illegible]ions			
PLOT NAME = Fabrication Drawing	GENERATED : 8/24/2017 1:34:02 PM	TEXAS INSTRUMENTS	

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ENGINEER:	LAYOUT BY:
Daniel Ruiz	Daniel Ruiz
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.1.12.290